> 3rd generation version of still-popular Xinger® and Xinger®-II SMT components = high-performance option
> At 1/4 the size (as small as 0.25 x 0.20”), same power handling as previous generations – plus lower loss, higher isolation, better phase/amplitude balance, and other performance advantages
> Supports complete range of bands, including WiMax, 3G, 4G, LTE, among many others
> Superior CTE characteristics relative to ceramics – no solder cracking, no need for costly high-performance PCB
> 100% RF-tested
> Shipped on tape and reel for automated, high-volume assembly
> RoHS compliant
> More!
Introducing the Xinger®-III brand family of surface-mount hybrid and directional couplers, our latest, innovation-driven reinvention of the SMT RF coupler – and designed especially for today’s higher-power, more compact, and hotter-running equipment.

Matter of fact, inch for inch, watt for watt, the Xinger-III family offers the highest performance of any softboard coupler on the market... even when compared to similarly sized members of our own category-leading, Xinger-II family.

> **Xinger-III hybrids** offer up to 5.35 times the power-handling ability; 52-66% lower insertion loss (down to 0.12dB); 25-28% higher isolation; and 63-71% better amplitude balance.

> **Xinger-III directionals** offer 37-64% lower insertion loss (down to 0.05dB); same directivity; and 50% higher power handling at 1/4 the size.

Best of all, Xinger-III technology now makes softboard THE best alternative for all power levels, including very high-power applications over 200W. And because our CTE characteristics match those of your board (unlike ceramic couplers!), you don't have to worry about CTE mismatch and solder joint cracking that can result with ceramic coupler implementations.

Interested in leveraging the latest generation of Xinger-brand SMT softboard couplers from the company who invented them in the first place? Email, call, or visit our website today for samples, a quote, or applications assistance.
Learn how to put our latest generation Xinger®-brand components to work for your latest-generation design! Email, call, or visit our website today for samples, a quote, or applications assistance.
Beyond our ever-popular Xinger®-brand components, count on Anaren’s 40+ years of RF/microwave experience for these other wireless solutions:

> **Xinger®-brand, subminiature components** – sized for today’s compact wireless infrastructure and consumer electronics – including couplers, balun transformers, and power dividers.

> **Anaren Integrated Radio (AIR) modules** – an easier, more elegant, and cost-effective way for E-OEM design engineers to bring RF/wireless capability to new or existing devices.

> **Wireless resistive components** – ‘lowest-cost’ line of terminations, attenuators, and resistors for high-volume application; available in a wide range of form factors, all of them constructed of RoHS compliant material.

> **Military and instrumentation resistive components** – high-performance, high-powerhandling resistive parts suitable to your toughest application. Choose from chip, SMT, flanged, flangeless.

> **Components, assemblies & custom solutions for defense** – including military-grade Xinger®-brand SMT couplers, cased/caseless components, ferrites, DRFMs, DFDs, multi-chip RF modules, IMAs, and more!

> **Custom wireless assemblies** – including splitter/combiners, RF backplanes, ferrites, more!

To learn more about Anaren – a leading, worldwide provider of high-frequency technology to the wireless, consumer electronics, aerospace, medical device, and other industries – email sales@anaren.com or visit our website today.